



# SGM7223

## High Speed USB 2.0 (480Mbps) DPDT Analog Switch

### GENERAL DESCRIPTION

The SGM7223 is a DPDT (double-pole/double-throw) analog switch. It operates from a 1.8V to 4.3V single power supply. Each switch of the SGM7223 is bidirectional, which can ensure that the high speed signals have little or no attenuation at the outputs.

The SGM7223 features high speed, low bit-to-bit skew and wide bandwidth. The high performances make it very suitable for multiple applications, such as cellular phones and computer peripherals, etc.

The SGM7223 has a power-off protection. It can prevent accidental signal leakage and ensure system reliability under power-down and over-voltage conditions. In addition, the device is capable of withstanding a  $V_{BUS}$  short to D+ or D- when the device is either powered on or powered off because of the special circuitry on the D+/D- pins.

The SGM7223 is available in a Green TQFN-2.1×1.6-10L package. It operates over an ambient temperature range of -40°C to +85°C.

### APPLICATIONS

Cellular Phones  
Digital Cameras  
Portable Equipment  
Computer Peripherals  
Battery-Powered Systems  
Routes Signals for USB 2.0 Full-Speed

### FEATURES

- **Supply Voltage Range:** 1.8V to 4.3V
- **On-Resistance:** 4.5Ω (TYP) at 3V
- **-3dB Bandwidth:** 500MHz
- **Low Bit-to-Bit Skew:** 50ps (TYP)
- **Fast Switching Times:**
  - $t_{ON}$ : 11ns
  - $t_{OFF}$ : 20ns
- **High Off-Isolation:** -30dB ( $R_L = 50\Omega$ ,  $f = 250\text{MHz}$ )
- **Low Crosstalk:** -33dB ( $R_L = 50\Omega$ ,  $f = 250\text{MHz}$ )
- **Power-Off and Power-On Protections**
- **Rail-to-Rail Input and Output Operation**
- **Break-Before-Make Switching**
- **-40°C to +85°C Operating Temperature Range**
- **Available in a Green TQFN-2.1×1.6-10L Package**

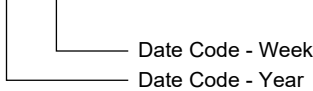
**PACKAGE/ORDERING INFORMATION**

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM7223	TQFN-2.1x1.6-10L	-40°C to +85°C	SGM7223YTQD10/TR	7223 XXXX	Tape and Reel, 3000

**MARKING INFORMATION**

NOTE: XXXX = Date Code.

**XXXX**



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

**ABSOLUTE MAXIMUM RATINGS**

- V+, IN to GND.....0V to 4.6V
- Analog, Digital Voltage Range ..... -0.3V to (V+) + 0.3V
- Continuous Current HSDn or Dn ..... ±100mA
- Peak Current HSDn or Dn ..... ±150mA
- Junction Temperature ..... +150°C
- Storage Temperature Range ..... -65°C to +150°C
- Lead Temperature (Soldering, 10s) ..... +260°C
- ESD Susceptibility
- HBM..... 4000V
- MM..... 400V

**RECOMMENDED OPERATING CONDITIONS**

- Operating Temperature Range ..... -40°C to +85°C

**OVERSTRESS CAUTION**

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

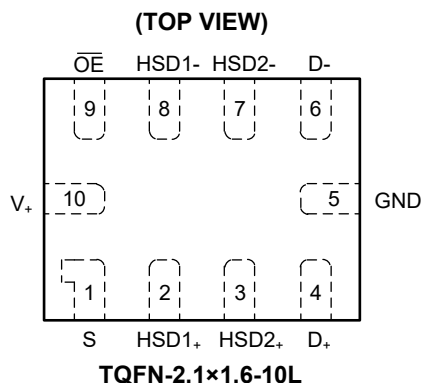
**ESD SENSITIVITY CAUTION**

This integrated circuit can be damaged by ESD if you don't pay attention to ESD protection. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

**DISCLAIMER**

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

## PIN CONFIGURATION



## PIN DESCRIPTION

PIN	NAME	FUNCTION
1	S	Select Input Pin.
2, 3, 8, 7, 4, 6	HSD1+, HSD2+, HSD1-, HSD2-, D+, D-	Data Ports.
5	GND	Ground.
9	$\overline{\text{OE}}$	Output Enable Control Pins.
10	V <sub>+</sub>	Positive Power Supply.

## FUNCTION TABLE

$\overline{\text{OE}}$	S	HSD1+ HSD1-	HSD2+ HSD2-
0	0	ON	OFF
0	1	OFF	ON
1	x	OFF	OFF

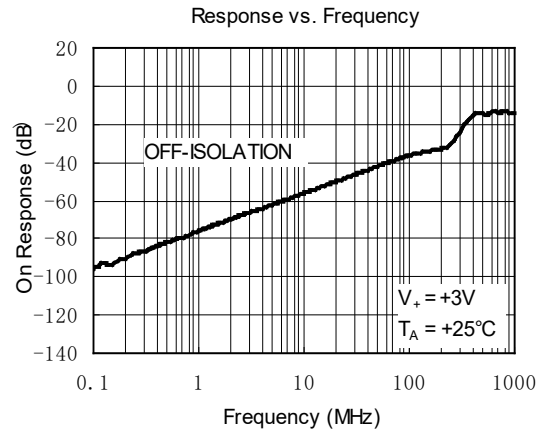
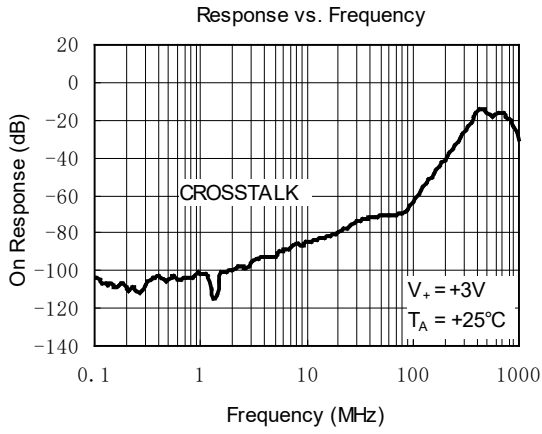
NOTE: Switches Shown For Logic "0" Input.

## ELECTRICAL CHARACTERISTICS

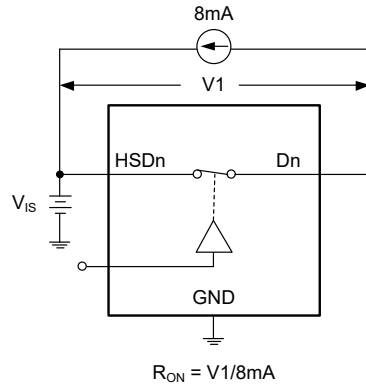
( $V_+ = 1.8V$  to  $4.3V$ ,  $GND = 0V$ ,  $V_{IH} = 1.6V$ ,  $V_{IL} = 0.5V$ , Full =  $-40^\circ C$  to  $+85^\circ C$ . Typical values are at  $V_+ = 3.3V$ ,  $T_A = +25^\circ C$ , unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS
<b>Analog Switch</b>							
Analog I/O Voltage (HSD1+, HSD1-, HSD2+, HSD2-)	$V_{IS}$		Full	0		$V_+$	V
On-Resistance	$R_{ON}$	$V_+ = 3V$ , $V_{IS} = 0V$ to $0.4V$ , $I_D = 8mA$ , Test Circuit 1	+25°C		4.5	8.5	Ω
			Full			9	
On-Resistance Match between Channels	$\Delta R_{ON}$	$V_+ = 3V$ , $V_{IS} = 0V$ to $0.4V$ , $I_D = 8mA$ , Test Circuit 1	+25°C		0.2	0.6	Ω
			Full			1.5	
On-Resistance Flatness	$R_{FLAT(ON)}$	$V_+ = 3V$ , $V_{IS} = 0V$ to $1.0V$ , $I_D = 8mA$ , Test Circuit 1	+25°C		1.8	2.2	Ω
			Full			2.8	
Power Off Leakage Current (D+, D)	$I_{OFF}$	$V_+ = 0V$ , $V_D = 0V$ to $3.6V$ , $V_S$ , $V_{OE} = 0V$ or $3.6V$	Full			1	μA
Increase in $I_+$ per Control Voltage	$I_{CCT}$	$V_+ = 3.6V$ , $V_S$ or $V_{OE} = 2.6V$	Full			5	μA
Source Off Leakage Current	$I_{HSD2(OFF)}$ , $I_{HSD1(OFF)}$	$V_+ = 3.6V$ , $V_{IS} = 3.3V/0.3V$ , $V_D = 0.3V/3.3V$	Full			1	μA
Channel On Leakage Current	$I_{HSD2(ON)}$ , $I_{HSD1(ON)}$	$V_+ = 3.6V$ , $V_{IS} = 3.3V/0.3V$ , $V_D = 3.3V/0.3V$ or floating	Full			1	μA
<b>Digital Inputs</b>							
Input High Voltage	$V_{IH}$		Full	1.6			V
Input Low Voltage	$V_{IL}$		Full			0.5	V
Input Leakage Current	$I_{IN}$	$V_+ = 3V$ , $V_S$ , $V_{OE} = 0V$ or $V_+$	Full			1	μA
<b>Dynamic Characteristics</b>							
Turn-On Time	$t_{ON}$	$V_{IS} = 0.8V$ , $R_L = 50\Omega$ , $C_L = 10pF$ , Test Circuit 2	+25°C		11		ns
Turn-Off Time	$t_{OFF}$		+25°C		20		ns
Break-Before-Make Time Delay	$t_D$	$V_{IS} = 0.8V$ , $R_L = 50\Omega$ , $C_L = 10pF$ , Test Circuit 3	+25°C		5		ns
Propagation Delay	$t_{PD}$	$R_L = 50\Omega$ , $C_L = 10pF$	+25°C		0.3		ns
Off Isolation	$O_{ISO}$	Signal = 0dBm, $R_L = 50\Omega$ , $f = 250MHz$ , Test Circuit 4	+25°C		-30		dB
Channel-to-Channel Crosstalk	$X_{TALK}$	Signal = 0dBm, $R_L = 50\Omega$ , $f = 250MHz$ , Test Circuit 5	+25°C		-33		dB
-3dB Bandwidth	BW	Signal = 0dBm, $R_L = 50\Omega$ , $C_L = 5pF$ Test Circuit 6	+25°C		500		MHz
Channel-to-Channel Skew	$t_{SKEW}$	$R_L = 50\Omega$ , $C_L = 10pF$	+25°C		0.05		ns
Charge Injection Select Input to Common I/O	Q	$V_G = GND$ , $C_L = 1nF$ , $R_G = 0\Omega$ , $Q = C_L \times V_{OUT}$ , Test Circuit 7	+25°C		9.8		pC
HSD+, HSD-, D+, D. On Capacitance	$C_{ON}$		+25°C		6.5		pF
<b>Power Requirements</b>							
Power Supply Range	$V_+$		Full	1.8		4.3	V
Power Supply Current	$I_+$	$V_+ = 3V$ , $V_S$ , $V_{OE} = 0V$ or $V_+$	Full			1	μA

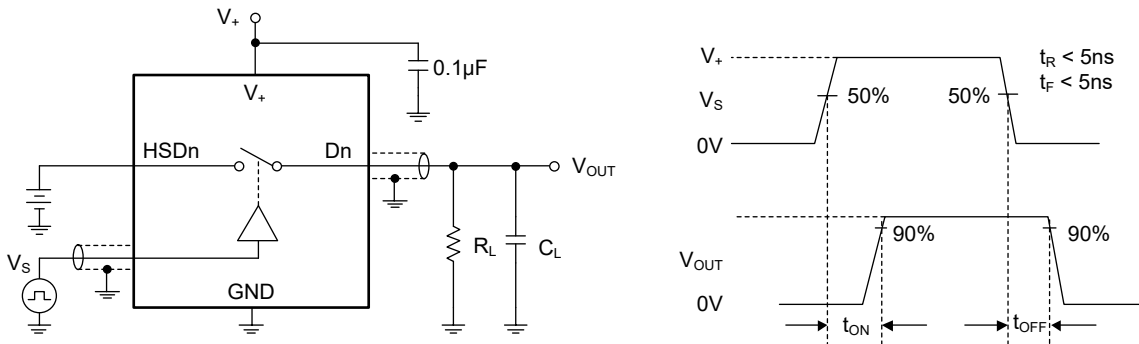
TYPICAL PERFORMANCE CHARACTERISTICS



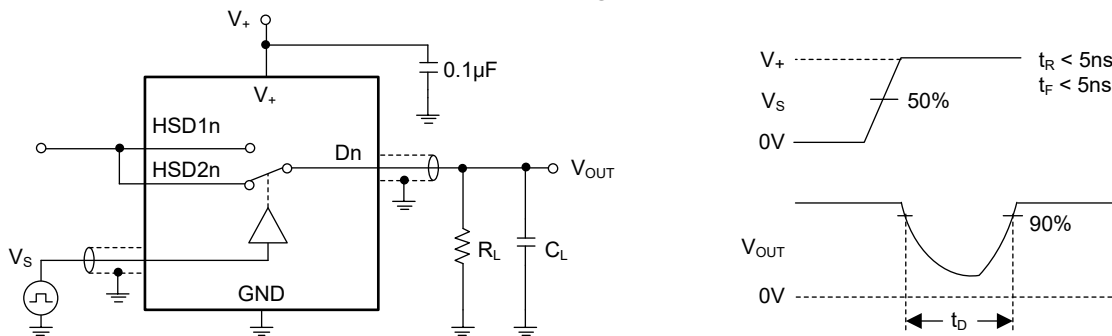
TEST CIRCUITS



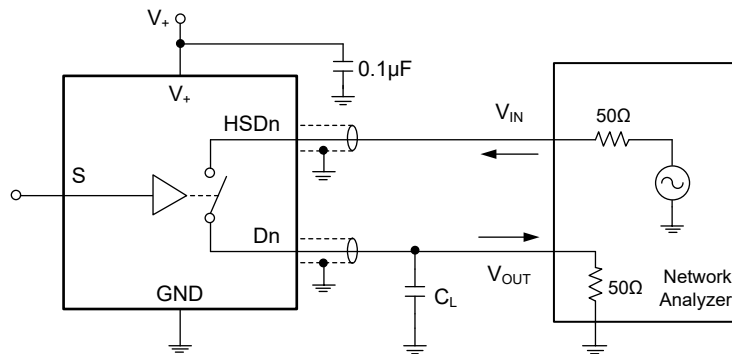
Test Circuit 1. On-Resistance



Test Circuit 2. Switching Times ( $t_{ON}$ ,  $t_{OFF}$ )

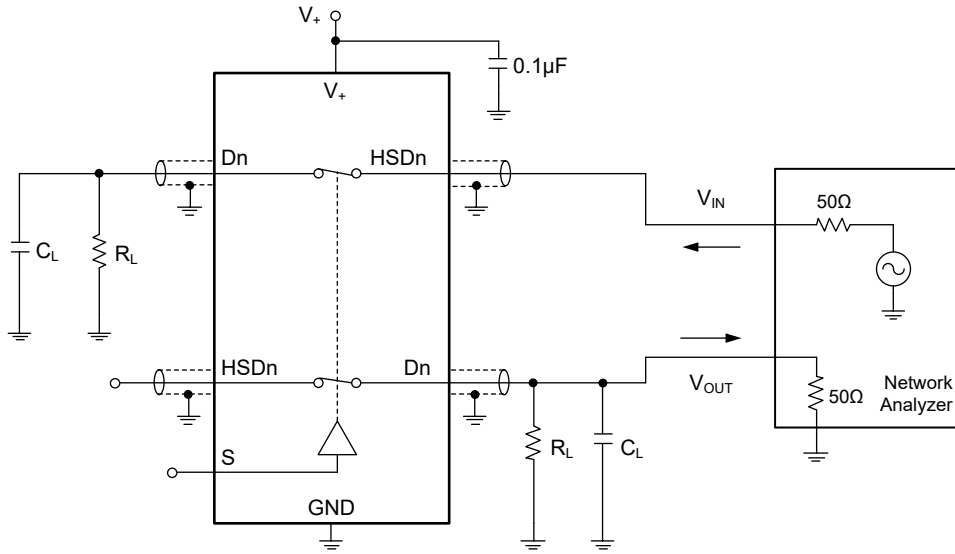


Test Circuit 3. Break-Before-Make Time ( $t_D$ )



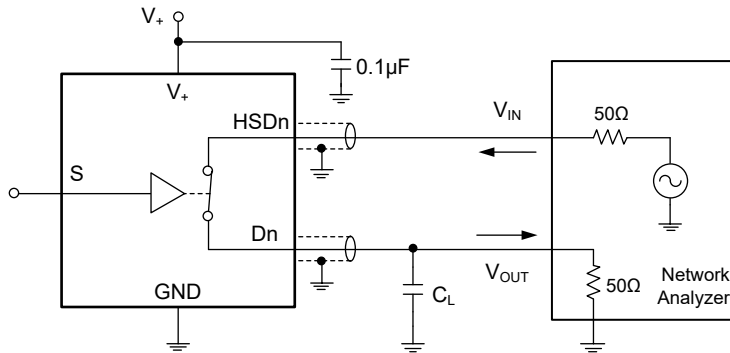
Test Circuit 4. Off Isolation

TEST CIRCUITS (continued)

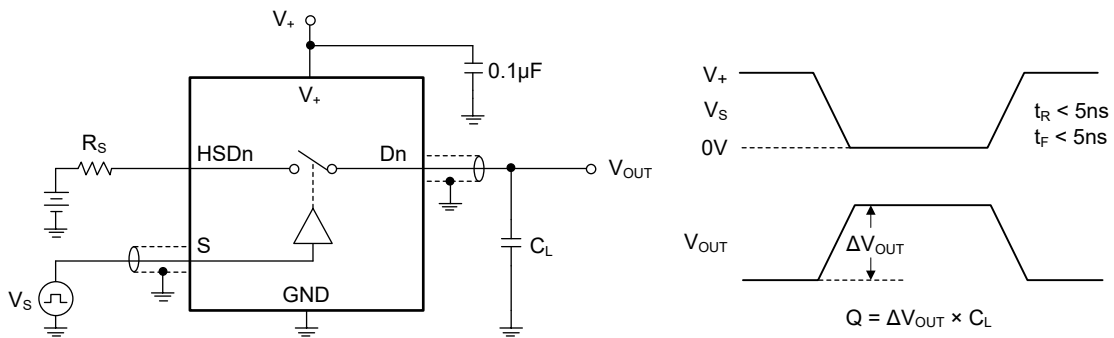


$$\text{Channel-to-Channel Crosstalk} = -20 \log (V_{\text{HSDn}}/V_{\text{OUT}})$$

Test Circuit 5. Channel-to-Channel Crosstalk



Test Circuit 6. -3dB Bandwidth



Test Circuit 7. Charge Injection (Q)

**APPLICATION INFORMATION**

**Meet the Short Requirements of USB 2.0**

**V<sub>BUS</sub>**

According to Section 7.1.1 of the USB 2.0 specification, USB devices must be able to withstand a V<sub>BUS</sub> short to D+ or D- when powered on or off. The SGM7223 can fully meet these two requirements

**Power-Off Protection**

When D+ or D- is shorted to V<sub>BUS</sub>, there is a special protection circuit inside the SGM7223, so that the device will not be damaged within 24 hours. In case of power-down or over-voltage event, the protection circuit can prevent the leakage signal on D+/D- pins to ensure the reliability of the system.

**Power-On Protection**

The USB 2.0 specification requires USB device to ensure that the device will not be damaged even if V<sub>BUS</sub> short-circuit occurs during data transmission. Therefore, under over-voltage conditions, the SGM7223 will limit the current flowing back to the V<sub>+</sub> track, and the current will not exceed the safe operating range.

**USB2.0 Signal Quality Compliance Test Results**

The results of USB eye map test are shown in Figure 1 and Figure 2. Table 1 gives a summary of the USB tests.

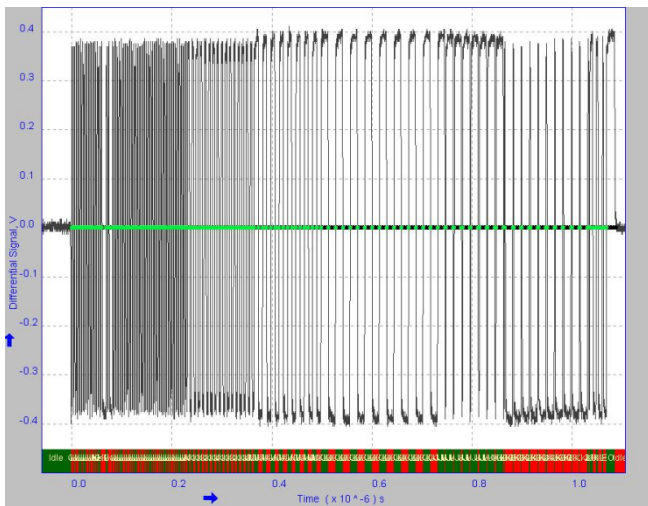


Figure 1. Waveform Plot

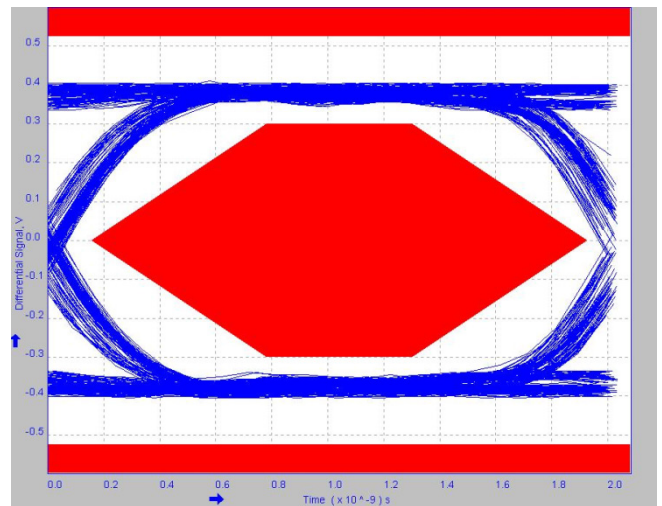


Figure 2. High Speed Signal Quality Eye Diagram Test (V<sub>+</sub> = 3.3V)

Table 1. Summary of the USB 2.0 Signal Quality Tests Results

Measurement Name	MIN	MAX	Mean	pk-pk	Standard Deviation	RMS	Population	Status
Eye Diagram Test	-	-	-	-	-	-	-	Pass
Signal Rate	467.3807 Mbps	496.5449 Mbps	479.9494 Mbps	0.0000 bps	6.174360 Mbps	480.4821 Mbps	512	Pass
EOP Width	-	-	16.61442ns	-	-	-	1	Pass
EOP Width (Bits)	-	-	7.974082	-	-	-	1	Pass
Falling Edge Rate	1.100184 kV/μs	1.304518 kV/μs	1.187936 kV/μs	204.3340 V/μs	52.11665 V/μs	1.189068 kV/μs	107	Pass
Rising Edge Rate	1.058148 kV/μs	1.232657 kV/μs	1.137964 kV/μs	174.5099 V/μs	46.35985 V/μs	1.138899 kV/μs	108	Pass

**Additional Information:**

Consecutive Jitter range: -115.0ps to 71.20ps RMS Jitter 40.26ps

KJ Paired Jitter range: -34.68ps to 29.00ps RMS Jitter 11.09ps

JK Paired Jitter range: -30.42ps to 35.73ps RMS Jitter 12.11ps

- Rising Edge Rate: 1.137964kV/μs (Equivalent Rise Time = 562.41ps)
- Falling Edge Rate: 1.187936kV/μs (Equivalent Fall Time = 538.75ps)



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## REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<b>MAY 2016 – REV.A.1 to REV.A.2</b>	<b>Page</b>
Added Recommended Land Pattern section .....	11
Added Tape and Reel Information section .....	12, 13

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<b>MAY 2011 – REV.A to REV.A.1</b>	<b>Page</b>
Updated package name .....	All

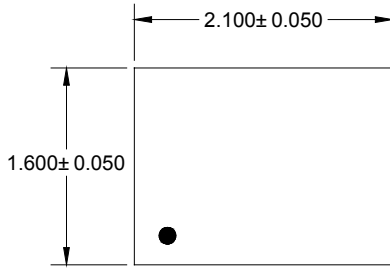
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<b>Changes from Original (AUGUST 2008) to REV.A</b>	<b>Page</b>
Changed from product preview to production data .....	All

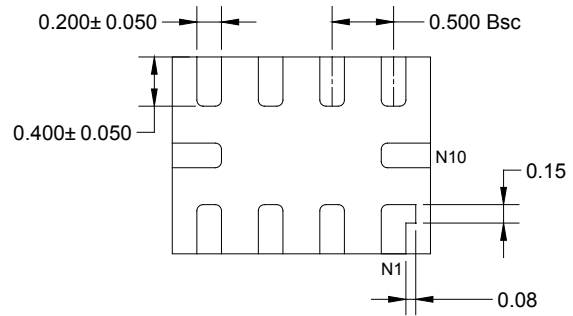
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**PACKAGE OUTLINE DIMENSIONS**

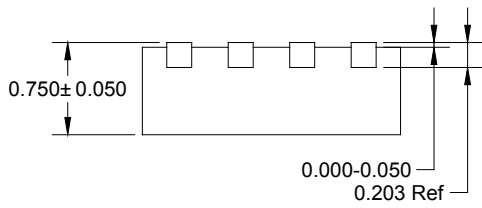
**TQFN-2.1×1.6-10L**



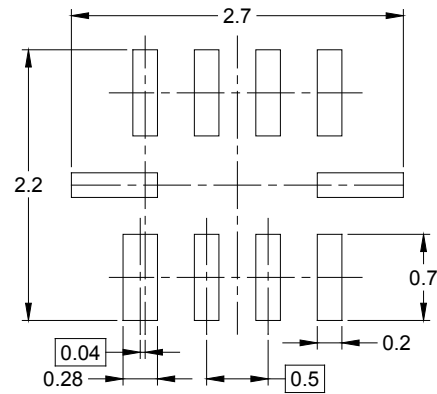
**TOP VIEW**



**BOTTOM VIEW**



**SIDE VIEW**



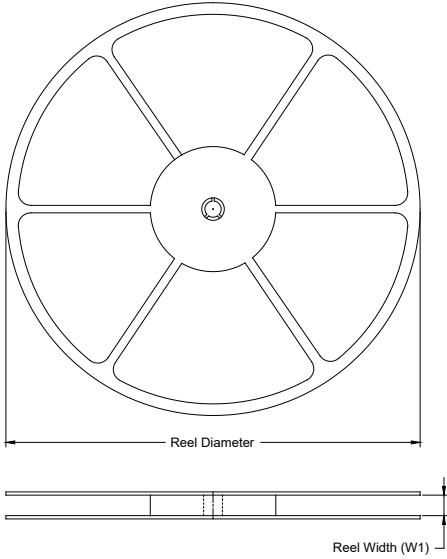
**RECOMMENDED LAND PATTERN**

NOTE: All linear dimensions are in millimeters.

# PACKAGE INFORMATION

## TAPE AND REEL INFORMATION

### REEL DIMENSIONS



### TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

### KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TQFN-2.1×1.6-10L	7"	9.0	1.90	2.30	0.90	4.0	4.0	2.0	8.0	Q1

DD0001

# PACKAGE INFORMATION

## CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

## KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
7" (Option)	368	227	224	8
7"	442	410	224	18

DD0002